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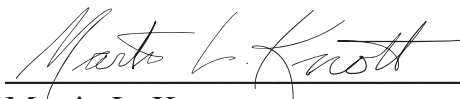
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Martin L. Knott
Metadata and Linked Data Strategist

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**A DESIGN PERSPECTIVE
SECOND EDITION**

**JAN M. RABAEY
ANANTHA CHANDRAKASAN
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*To Kathelijn, Karthiyayani, Krithivasan,
and our Parents*

"Qu'est-ce que l'homme dans la nature?

*Un néant a l'égard de l'infini,
un tout al l'égard du néant,
un milieu entre rien et tout."*

"What is man in nature?

*Nothing in relation to the infinite,
everything in relation to nothing,
a mean between nothing and everything."*

Blaise Pascal, *Pensées*, n. 4, 1670.

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While maintaining the spirit of the original, we have been preserving the spirit and style of the original design. This is a challenge, but it is one that we have accepted. We have been working to maintain the spirit of the original design, while also incorporating the latest in design technology. This is a challenge, but it is one that we have accepted. We have been working to maintain the spirit of the original design, while also incorporating the latest in design technology. This is a challenge, but it is one that we have accepted.

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